## **K0900S Series Sidac**

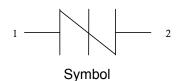
Rev.1.0

#### **DESCRIPTION:**

The sidac is a silicon bilateral voltage triggered switch with greater power-handling capabilities than standard diacs. Upon application of a voltage exceeding the sidac breakover voltage point, the sidac switches on through a negative resistance region to a low on-state voltage. Conduction continues until the current is interrupted or drops below the minimum holding current of the device.

### **APPLICATIONS:**

- ♦ High-voltage lamp ignitors
- ♦ Natural gas ignitors
- ♦ Gas oil ignitors
- ♦ High-voltage power supplies
- ♦ Xenon ignitors
- ♦ Overvoltage protector
- ♦ Pulse generators
- ♦ Fluorescent lighting ignitorsHID lighting ignitors



### **FEATURES:**

- ♦ Excellent capability of absorbing transient surge
- ♦ Quick response to surge voltage (ns Level)
- ♦ Glass-passivated junctions
- ♦ High voltage lcmp ignitors

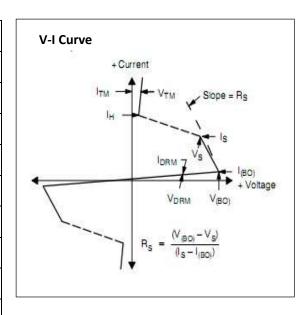
### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T <sub>stg</sub>	-40 to +125	$^{\circ}\!\mathbb{C}$
Operating junction temperature range	Tj	-40 to +125	$^{\circ}\!\mathbb{C}$
On-state RMS Current	I <sub>T</sub>	1	Α
Maximum surge on-state current non-repetitive one cycle peak value (50Hz)	I <sub>TSM</sub>	16.7	Α
Critical rate-of-rise of on-state current	di <sub>⊤</sub> /dt	80	А



# **ELECTRICAL CHARACTERISTICS** $(T_A=25^{\circ}C)$

Symbol	Parameter			
$V_{DRM}$	Peak off-state voltage			
I <sub>DRM</sub>	Off-state current			
Vs	Switching voltage			
Is	Switching current			
Rs	Switching resistance			
V <sub>T</sub>	On-state voltage			
I <sub>H</sub>	Holding current			
$V_{BO}$	Breakover Voltage			
I <sub>BO</sub>	Breakover current			

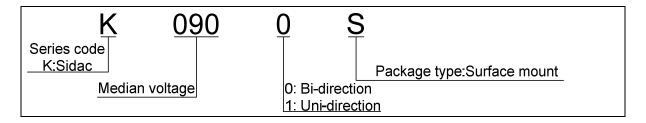


# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25°C, continued)

	I <sub>DRM</sub> @V <sub>DRM</sub>		$V_{BO}$		I <sub>BO</sub>	V <sub>T</sub> @ I <sub>T=</sub> 1A	I <sub>H</sub>	Rs	
Part Number	μΑ	V	\	/	uA	V	mA	kΩ	Marking
	max	min	min	max	max	max	min	min	
K0900S	1	70	80	97	50	2	10	0.1	K09S
K1050S	1	90	95	113	50	2	10	0.1	K10S
K1200S	1	100	110	125	50	2	10	0.1	K12S
K1300S	1	110	120	138	50	2	10	0.1	K13S
K1400S	1	120	130	146	50	2	10	0.1	K14S
K1500S	1	130	140	170	50	2	10	0.1	K15S
K1800S	1	160	170	195	50	2	10	0.1	K18S
K2000S	1	180	190	215	50	2	10	0.1	K20S
K2200S	1	190	205	230	50	2	10	0.1	K22S
K2400S	1	200	220	250	50	2	10	0.1	K24S
K2600S	1	220	240	270	50	2	10	0.1	K26S



## **ORDERING INFORMATION**



## **MARKING**

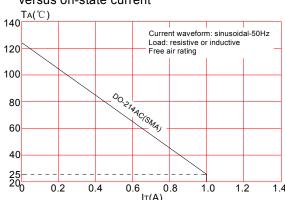


K09S:Device Marking Code 1409: In ninth week, 2014

## **SOLDERING PARAMETERS**

Reflow Condition		Pb-Free assembly (see FIG.2)	
	-Temperature Min (T <sub>s(min)</sub> )	+150℃	
Pre Heat	-Temperature Max(T <sub>s(max)</sub> )	+200℃	
	-Time (Min to Max) (ts)	60-180 secs.	
Average ramp	3℃/sec. Max		
T <sub>s(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3℃/sec. Max	
Reflow	-Temperature(T <sub>L</sub> ) (Liquid us)	+217℃	
	-Temperature(t <sub>L</sub> )	60-150 secs.	
Peak Temp (Tp	)	+260(+0/-5)°C	
Time within 5°C	8-15 secs.		
Ramp-down Rate		6℃/sec. Max	
Time 25°C to Peak Temp (T <sub>P</sub> )		8 min. Max	
Do not exceed		+260℃	

**FIG.1:** Maximum allowable ambient temperature versus on-state current



**FIG.3:** Normalized Vs change vs. junction temperature

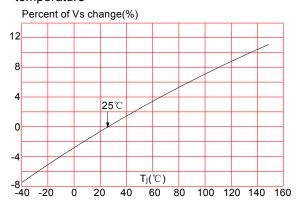
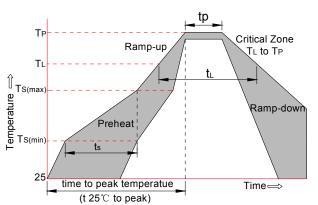
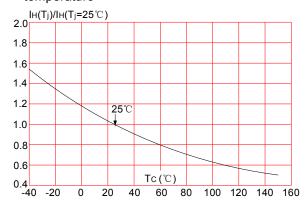


FIG.2: Reflow condition



**FIG.4:** Normalized DC holding current vs. case temperature



### TAPE AND REEL SPECIFICATION

PACKAGE	REEL (PCS)	PER CARTON (PCS)	REEL DIAMETERS (mm)
DO214AC/SMA	5,000	80,000	330
DO214AA/SMB	3,000	48,000	330

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